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General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	false
AEC-Q200	No
Typical Component Weight	790 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.012 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	83.3333 GOhms

Dimensions

Chip Size	3640
L	9.1mm +/-0.4mm
W	10.2mm +/-0.4mm
T	2mm +/-0.20mm
S	6.3mm MIN
B	1.27mm +/-0.4mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	250

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